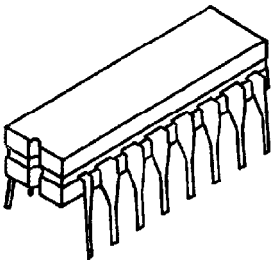


BRITISH STANDARDS INSTITUTION 2 PARK STREET, LONDON. W1A 2BS	BS CECC 90 104 - 137 ISSUE 1 DECEMBER 1981  Page 1 of 27 pages
Specification available from:- AS SHOWN IN PD 9002 AND CECC 00 200 AND ELECTRONIC COMPONENTS OF ASSESSED QUALITY DETAIL SPECIFICATION IN ACCORDANCE WITH: BS CECC 90 000 : 1976 BS CECC 90 100 : 1977	MANUFACTURERS TYPE NUMBER 4053B SEE PD 9002 AND CECC 00 200 For ordering information see page 11
Outline not to scale: Isometric projection Marking information see page 10  For detail dimensions see IEC 191-2 (A50C)	TRIPLE 2-CHANNEL ANALOG MULTIPLEXER/DEMULTIPLEXER SILICON COMPLEMENTARY MOS. WITH (B) BUFFERED OUTPUTS AND CAVITY PACKAGING. Assessment levels R, S, T and V and optional screening categories A, B, C and D

CAUTION: THESE ARE STATIC SENSITIVE DEVICES - See clause 1.11

1. Limiting conditions of use (not for inspection purposes)

All voltages referenced to V_{SS}

1.1	Maximum supply voltage, positive	V_{DD}	+18,0V
1.2	Maximum supply voltage, negative	V_{DD}	-0,5V
1.3	Maximum positive input voltage	V_I	V_{DD} +0,5V
1.4	Maximum negative input voltage	V_I	-0,5V

Refer to Qualified Products List PD 9002 and/or CECC 00 200 for details of manufacturers approved to this specification

1. Limiting conditions of use (contd)

1.5	Maximum power dissipation, per package per output	P_{D1}	200,0mW
		P_{D2}	66,66mA
1.6	Maximum continuous current into any input.	$ I_I $	10,0mA
1.7	Maximum continuous current into any output.	$ I_O $	10,0mA
1.8	Operating temperature range	T_{amb}	
		Full	-55 to +125°C
		Limited	-40 to + 85°C
1.9	Storage temperature range	T_{stg}	-65 to 150°C
1.10	Transient energy rating		400V at 100pF through 1,5kΩ
1.11	<u>Recommended handling precautions</u>		
1.11.1	Store devices in either conductive foam or conductive rails, or connect all leads together using a similar electrical shorting method.		
1.11.2	Use grounded tip soldering irons.		
1.11.3	Ground all test equipment		
1.11.4	Connect all unused device inputs to V_{DD} or V_{SS} .		
1.11.5	PC boards used to mount MOS devices should have all metal leads grounded during device mounting or flow soldering operations.		
1.11.6	Soldering equipment, solder pots or flow soldering equipment should be grounded whenever in contact with PC boards and/or MOS devices.		
1.11.7	Do not use ungrounded automatic insertion equipment or other handling equipment that precludes the use of suitable device lead grounding techniques during inspection or handling.		
1.11.8	When PC boards containing mounted MOS devices are removed from equipment for test, shipping or storage, 'Dummy connectors' should be used to electrically short all PC board terminals together.		
1.11.9	Switch off power supply before inserting or removing devices from circuits.		
1.11.10	Disconnect all low impedance equipment and input signals from the device before d.c. power supplies are switched off.		

2. Recommended conditions of use and associated characteristics (not for inspection purposes)

These apply over the operating temperature range unless otherwise stated. All voltages referenced to V_{SS} .

Characteristics	Conditions	Symbol	$V_{DD}(V)$	T_{amb} LOW	T_{amb} = 25°C	T_{amb} HIGH	Unit
Quiescent device current	$V_{IL} = 0V$ $V_{IH} = V_{DD}$						
Full temperature range	Outputs open circuit	I_{DDA}	5,0	0,25	0,25	7,5	μA
		I_{DDA}	10,0	0,50	0,50	15,0	μA
		I_{DDA}	15,0	1,00	1,00	30,0	μA
Limited temperature range		I_{DDA}	5,0	1,0	1,0	7,5	μA
		I_{DDA}	10,0	2,0	2,0	15,0	μA
		I_{DDA}	15,0	4,0	4,0	30,0	μA
Switch 'ON' level resistance	$(R_L = 10k\Omega)$ Inhibit = V_{SS} $V_{IN} = V_{SS}$ to V_{DD} $I_{IN} = 10,0\mu A$ 'ON' conditions at output obtained as Table 1						
Full temperature range		$r_{DS(ON)A}$	5,0	2000,0	2500,0	3500,0	Ω
		$r_{DS(ON)A}$	10,0	310,0	500,0	580,0	Ω
		$r_{DS(ON)A}$	15,0	220,0	280,0	400,0	Ω
Limited temperature range		$r_{DS(ON)A}$	5,0	2100,0	2500,0	3200,0	Ω
		$r_{DS(ON)A}$	10,0	450,0	500,0	520,0	Ω
		$r_{DS(ON)A}$	15,0	250,0	280,0	360,0	Ω
Switch 'OFF' level leakage current Any channel	$V_{IN}, V_{OUT} = V_{DD}$						
Full temperature range		$I_{S(OFF)A}$	15,0	500,0	200,0	500,0	nA
		$I_{D(OFF)A}$					
Limited temperature range		$I_{S(OFF)A}$	15,0	1000,0	1000,0	3000,0	nA
		$I_{D(OFF)A}$					

Characteristics	Conditions	Symbol	V _{DD} (V)	T _{amb} LOW	T _{amb} = 25°C	T _{amb} HIGH	Unit
Variation of Switch 'ON' level resistance 'ON' conditions at output obtained as Table 1.	$\pm V_{IN} = V_{EE} + 1,5V$ $I_{IN} = 10,0\mu A$ $\pm V_{IN} = 0V$ $\pm V_{IN} = V_{DD} - 1,5V$	$\Delta r_{DS(ON)A}$	5,0	200,0	200,0	500,0	Ω
	$\pm V_{IN} = V_{EE} + 2,0V$ $I_{IN} = 10,0\mu A$ $\pm V_{IN} = 0V$ $\pm V_{IN} = V_{DD} - 2,0V$	$\Delta r_{DS(ON)A}$	10,0	50,0	50,0	125,0	Ω
	$\pm V_{IN} = V_{EE} + 2,5V$ $I_{IN} = 10,0\mu A$ $\pm V_{IN} = 0V$ $\pm V_{IN} = V_{DD} - 2,5V$	$\Delta r_{DS(ON)A}$	15,0	50,0	50,0	125,0	Ω
	$V_{IL} = 0V$ $V_{IH} = V_{DD}$						
	Full temperature range	$ I_{IA} $	15,0	0,10	0,10	1,00	μA
	Limited temperature range	$ I_{IA} $	15,0	0,30	0,30	1,00	μA
	Input capacitance per unit load (Any input)	C_{IA}	-	-	7,5	-	pF
	Propagation and Transition Times						
	$C_L = 50pF$ (Test conditions as in Sub-group A5)						
Propagation Delay Time Switch Input to Switch Output Propagation Delay Time Inhibit to Signal Output Output HIGH or LOW to high impedance or high impedance to HIGH or LOW level	$R_L = 10k\Omega$	t_{PSA}	5,0	-	65,0	-	ns
		t_{PSA}	10,0	-	20,0	-	ns
		t_{PSA}	15,0	-	15,0	-	ns
	$R_L = 10k\Omega$	$t_{ON1A}/$	5,0	-	720,0	-	ns
		t_{OFF1A}	10,0	-	320,0	-	ns
			15,0	-	240,0	-	ns

Characteristics	Conditions	Symbol	$V_{DD}(V)$	T_{amb} LOW	T_{amb} = 25°C	T_{amb} HIGH	Unit
Propagation Delay Time Control Input to Switch Output	$R_L = 10k\Omega$	$t_{ON2A}/$	5,0	-	720,0	-	ns
		t_{OFF2A}	10,0	-	320,0	-	ns
			15,0	-	240,0	-	ns
Bandwidth at 3dB (Channel in 'ON' level)	$R_L = 1k\Omega$ $V_{IN} = 5,0V$ p-p	f_{1B}	10,0	-	44,0	-	MHz

Terminal identification

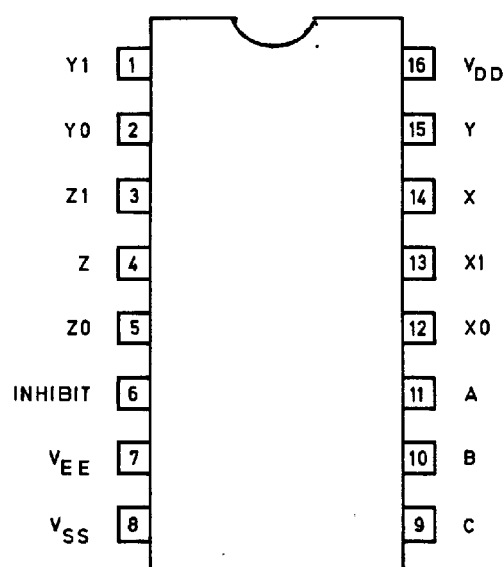


Figure 1

Function table

(Positive logic)

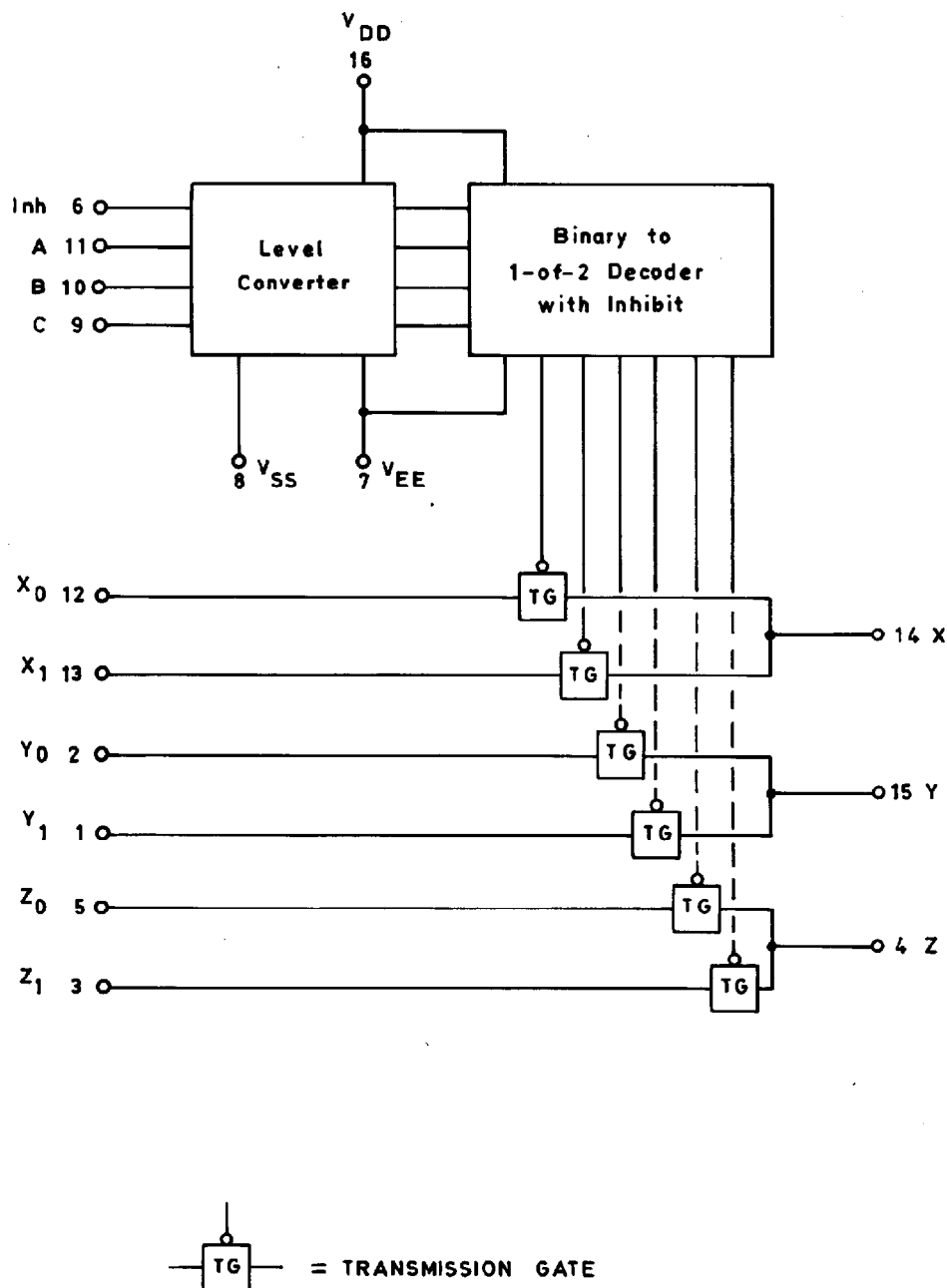
CONTROL INPUTS						
INHIBIT	SELECT			ON SWITCHES		
	C	B	A			
L	L	L	L	Z0	Y0	X0
L	L	L	H	Z0	Y0	X1
L	L	H	L	Z0	Y1	X0
L	L	H	H	Z0	Y1	X1
L	H	L	L	Z1	Y0	X0
L	H	L	H	Z1	Y0	X1
L	H	H	L	Z1	Y1	X0
L	H	H	H	Z1	Y1	X1
H	X	X	X	None		

H = HIGH level

L = LOW level

X = Level irrelevant

Typical logic diagram



This is a graphic representation, not a circuit diagram

Figure 2

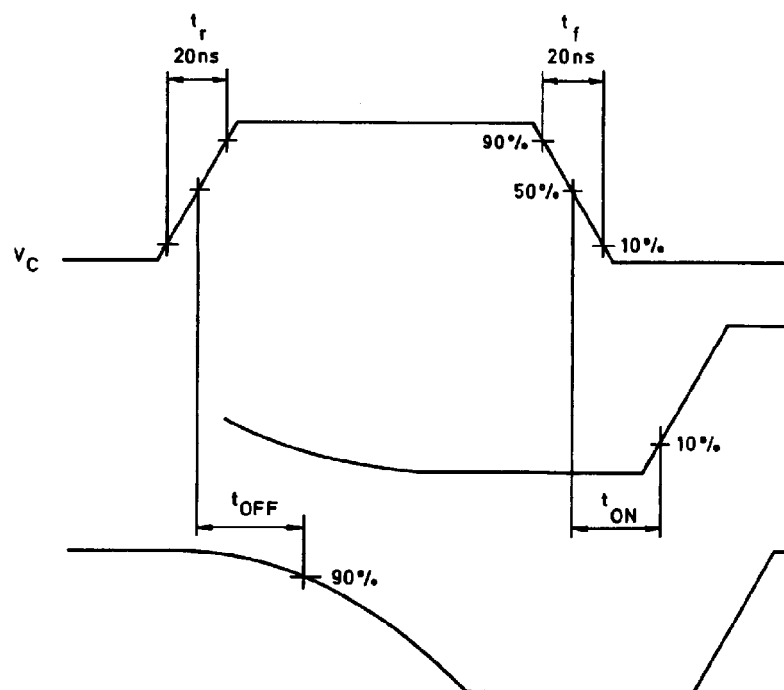
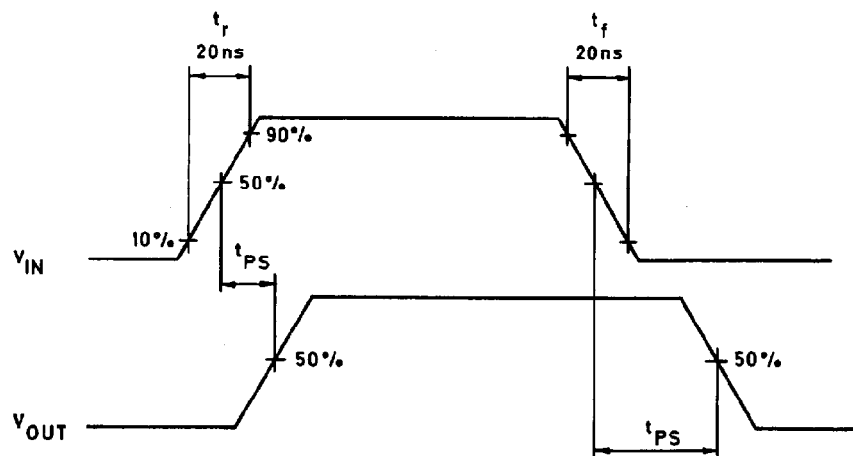


Figure 3

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Issue 1

Marking

The following shall be marked on the device, in the following order of precedence, as space permits. All information, except the terminal marking shall appear on the primary package used as initial protection or wrapping for delivery:

- (1) Terminal identification
- (2) Type number
- (3) Operating temperature range (if not included in 2)
- (4) Quality assessment level applied
- (5) Screening class applied
- (6) Date-code (year-week defined by three or four figures)
- (7) Mark of conformity (CECC logo)
- (8) Manufacturers name or trade mark (may include factory code)
- (9) Factory identification code
- (10) Package materials
- (11) Caution label for devices susceptible to damage by electrostatic discharge
- (12) Optional tests

The marking symbols shall be located following the figures below.

The underside of the package is free for manufacturers additional marking

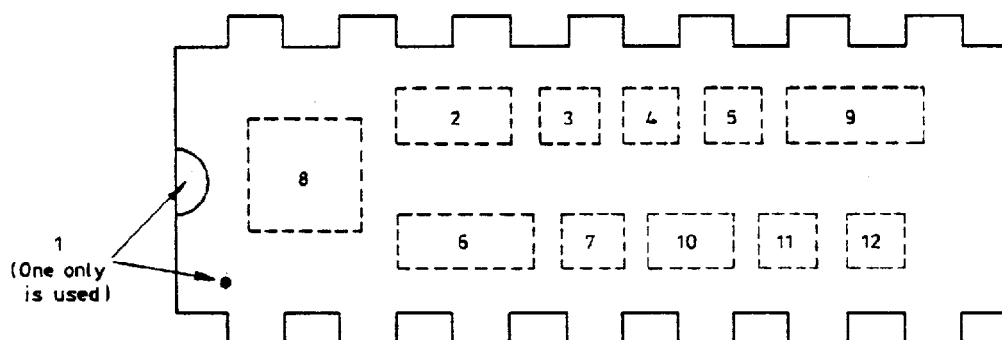


Figure 4